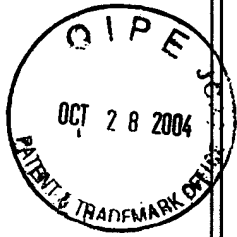


Appl. No. 09/944,732
Response dated October 22, 2004
Reply to Requirement for Information of August 18, 2004



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Lee John Smith et al.
Assignee: Amkor Technology, Inc.
Title: THIN SEMICONDUCTOR PACKAGE INCLUDING STACKED DIES
Serial No.: 09/944,732 Filed: August 31, 2001
Examiner: David E. Graybill Group Art Unit: 2822
Docket No.: G0079

Monterey, CA
October 22, 2004

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO REQUIREMENT FOR INFORMATION

Dear Sir:

This is response to the Requirement for Information
(Requirement) dated August 18, 2004:

1. **Remarks** begin on page 2 of this paper.